

SLOTOCOUP SF 70 电镀铜填孔

应对严苛载板制程的电镀铜解决方案

An electroplating copper solution for increasingly challenging substrate processes

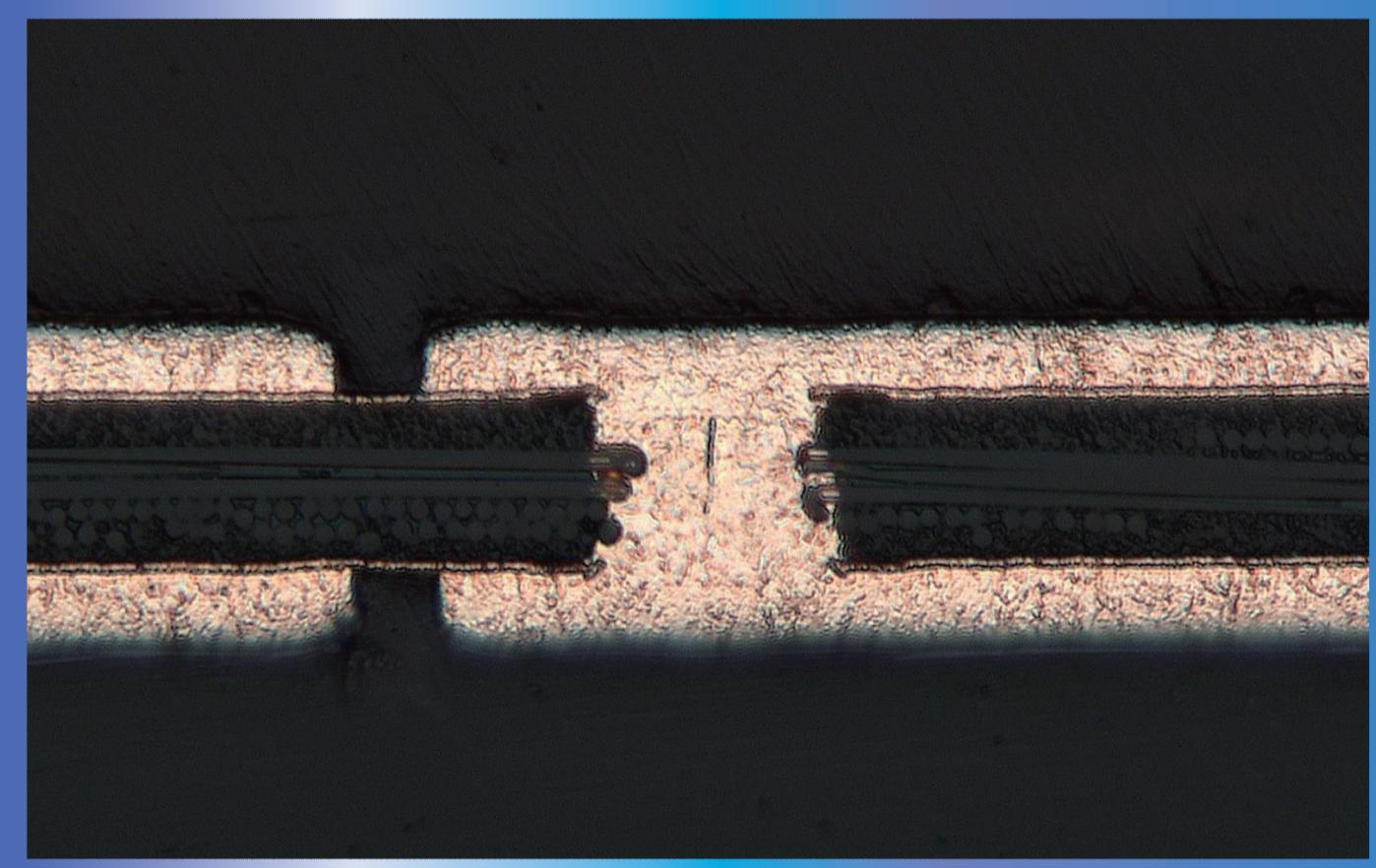
面对 PCB BT 载板制程日益严苛的填孔要求, SLOTOCOUP SF 70 能为您提供强大的支持。无论是应对高层数层或高纵深盲孔,还是不同纵身的填通孔设计,都能以出色的填孔能力和低铜厚覆盖性能,帮助您实现卓越的制程品质。

In response to the increasingly challenging via-filling requirements in substrate manufacturing, SLOTOCOUP SF 70 offers strong support. Able to deal with high stack layer or deep BMV design, or various depths of via-filling designs, its excellent filling capabilities and low copper thickness coverage help to achieve superior process quality.

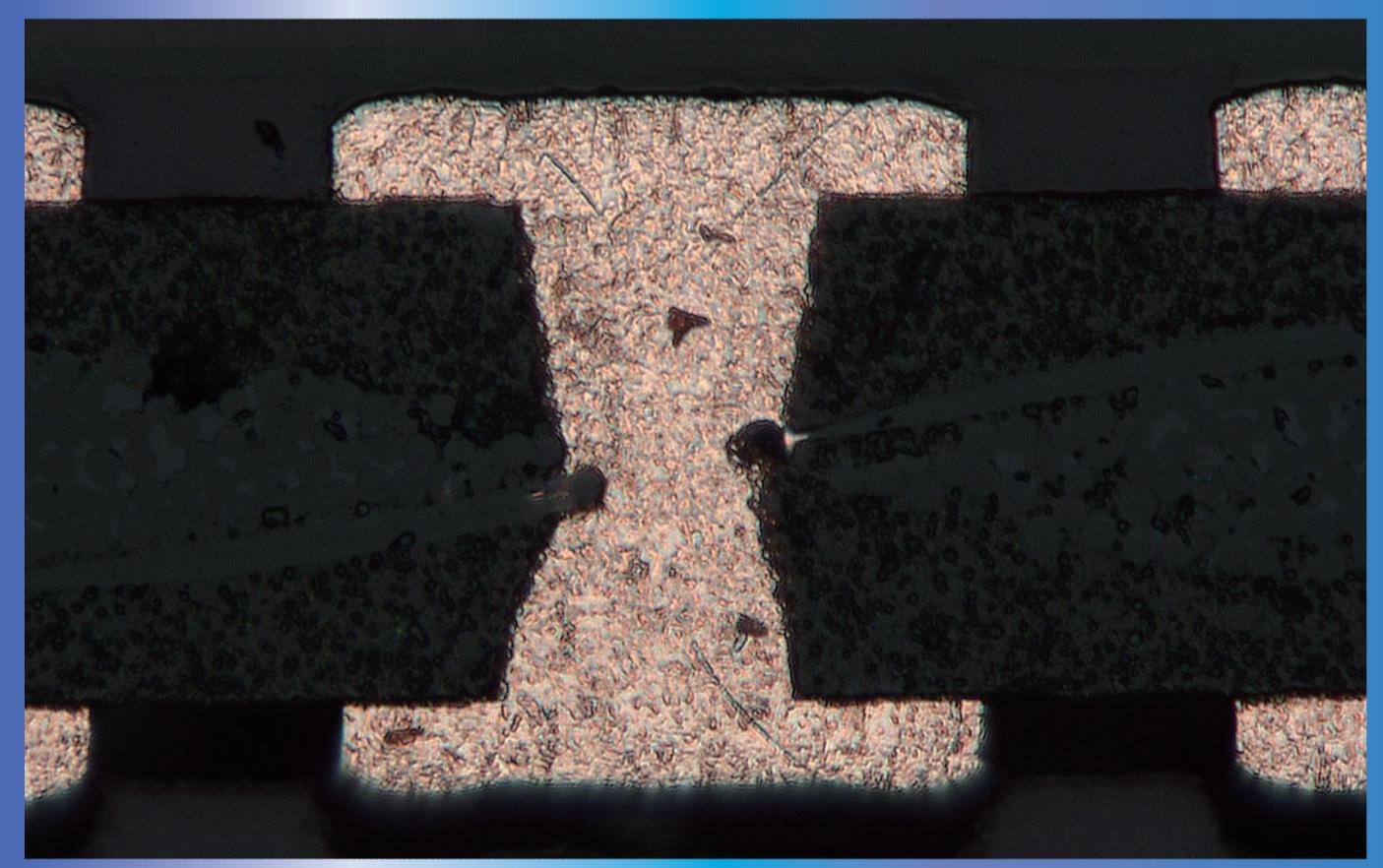
产品优势 Benefits

填孔能力强大可应对各种深度的盲孔及通孔设计, 确保铜厚分布均匀。

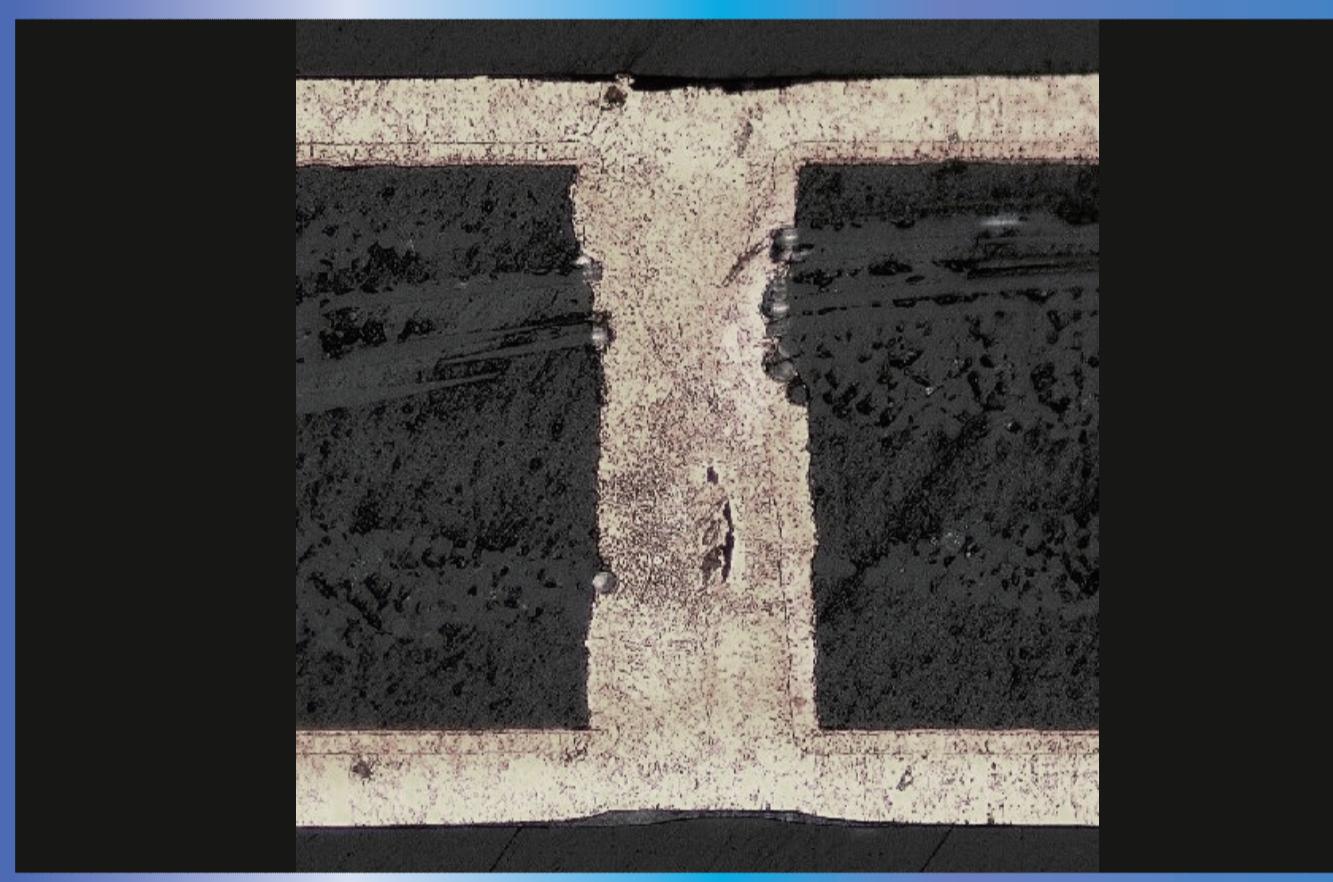
The strong filling capability can handle BMV & X-via designs of various depths, ensuring uniform copper thickness distribution.



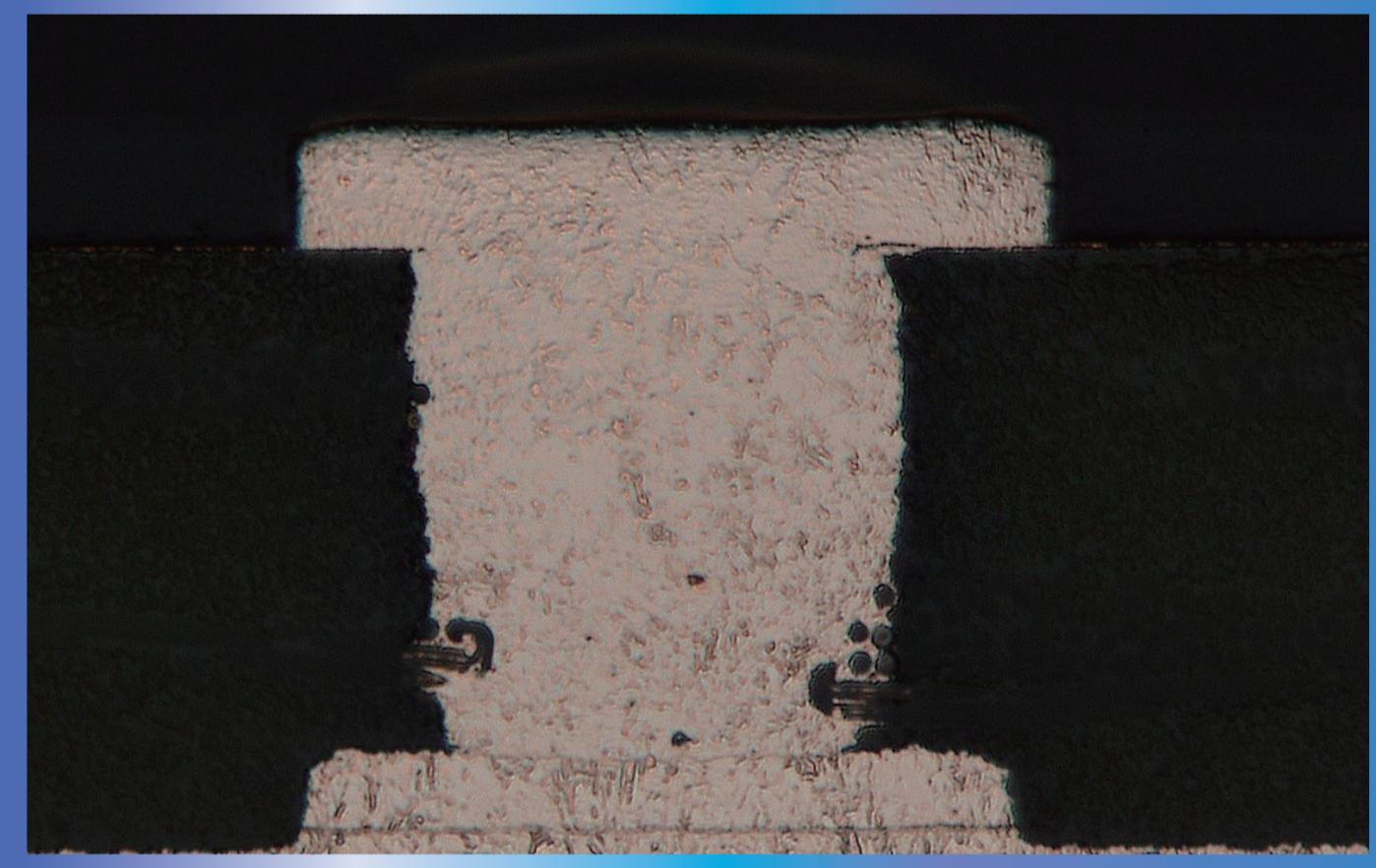
Ø 50µm PP35µm
THK 12µm
Dimple < 3µm



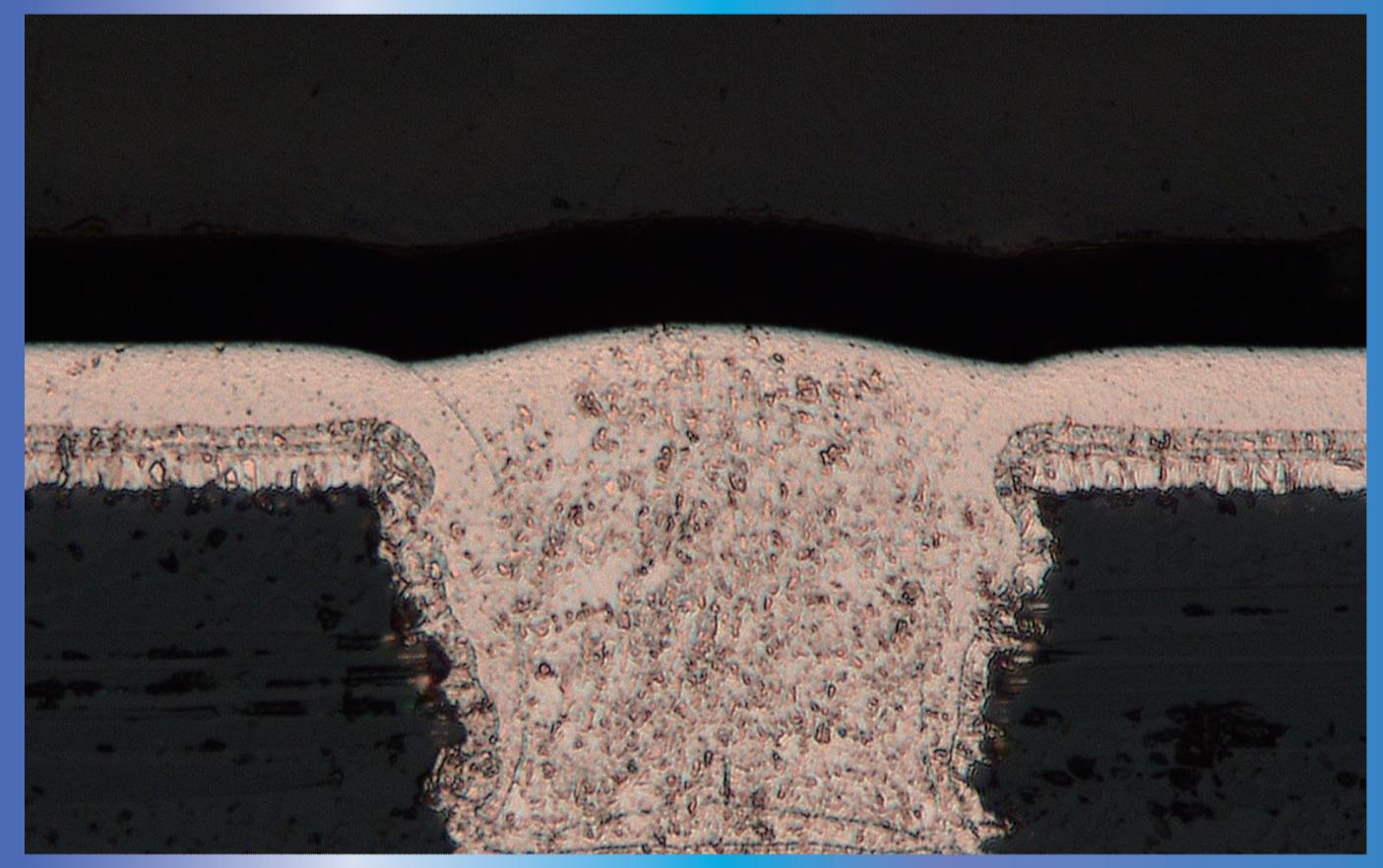
Ø 75µm PP100µm
THK 20µm
Dimple < 5µm



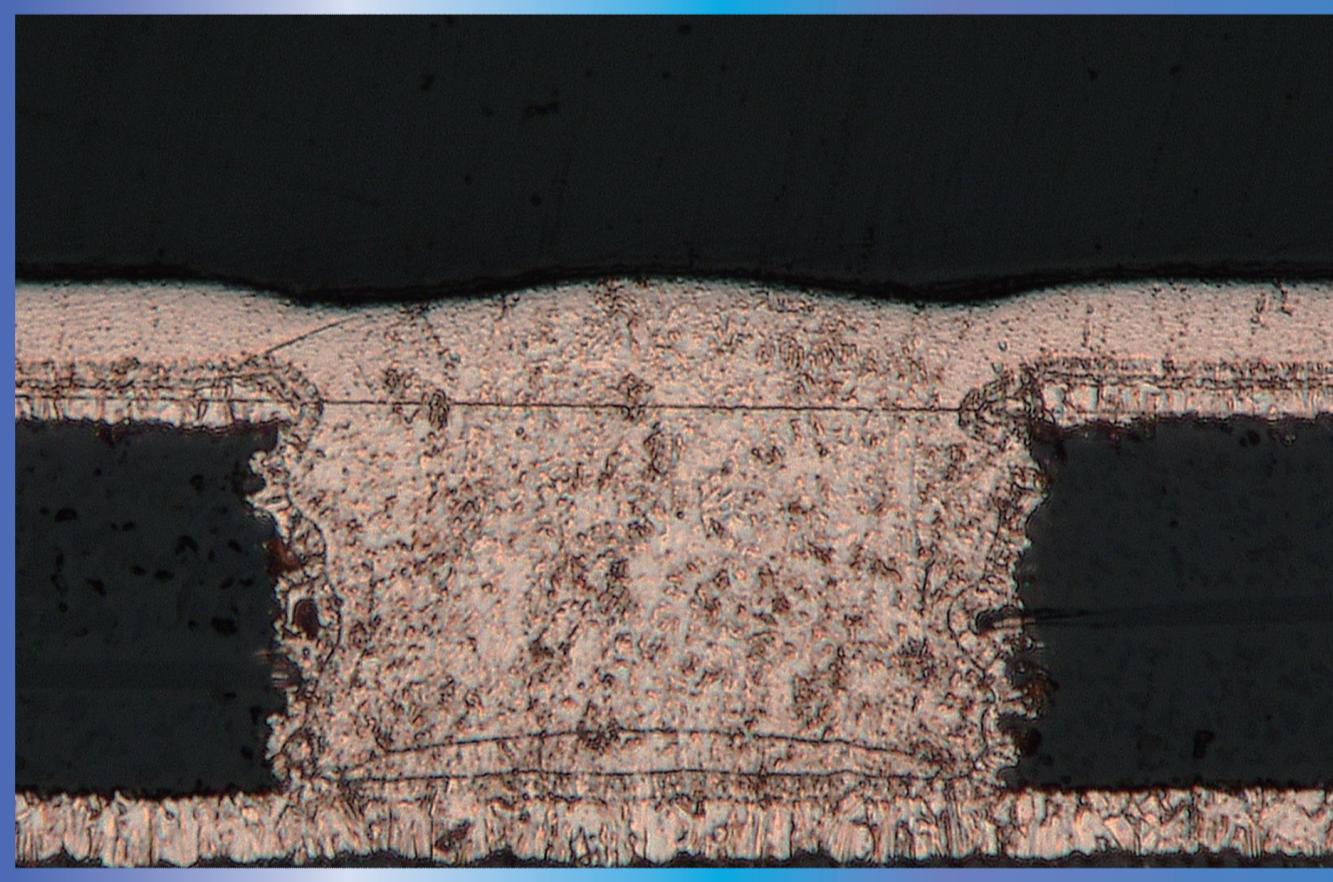
Ø 75µm PP200µm
THK 20µm
Dimple < 5µm



Ø 115µm PP100µm
THK 18µm
Dimple < 3µm



Ø 125µm PP80µm
THK 18µm



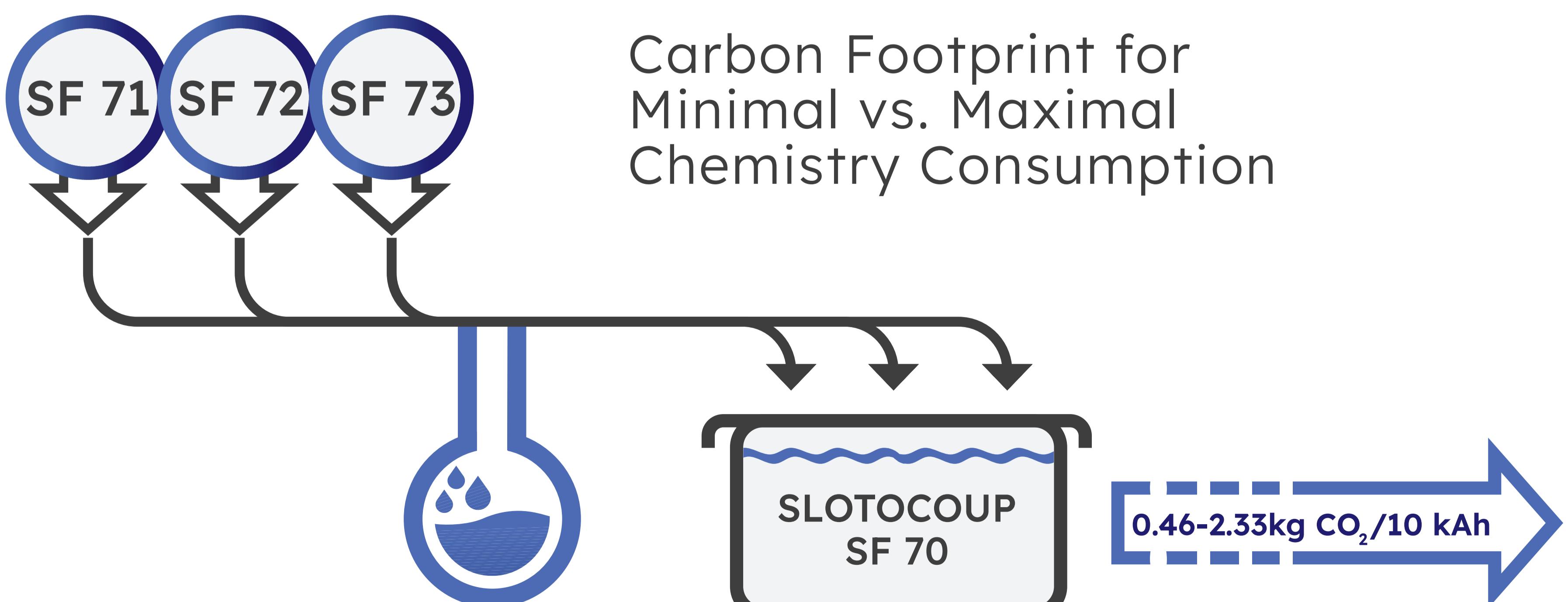
Ø 150µm PP80µm
THK 18µm

应用领域 Application

IC 载板
Mega scale unit IC
substrate

通讯载板
RF IC substrate

CO₂ 足迹 CO₂ Footprint



Carbon Footprint for
Minimal vs. Maximal
Chemistry Consumption